

TECHNICAL CAPACITIES

Rigid Printed Circuit Board	
Layers	1-40 layers
Minimum width track	3 mils – Copper thickness finished 25 µm
Minimum drilling diameter :	
Board thickness ≤ 1.2 mm	0,15 mm – drilling diameter
Board thickness ≤ 2.5 mm	0,20 mm – drilling diameter
Board thickness > 2.5 mm	Ratio aspect ≤ 13:1 – drilling diameter
Minimum mechanical drilling diameter	0.15 mm
Via laser minimum diameter	0.07 mm
Filled Via	With copper, tin, resin.
Specifics drilling	Blind, burried, half burried, pressfit, back drill.
Maximum panel size	650 x 1200 mm
Board thickness finished :	
Maximum thickness	10 mm
Min. 2 layers	0.2 mm
Min. 4 layers	0.35 mm
Min. 6 layers	0.55 mm
Controlled Impedance :	
Impedance tolerance	± 10% /Max >50 ohms +/- 5%
Imposed stackup	Imposed stackup or requested by customer out of standard production
Maximum copper thickness finished	420 µm
Surface finish	HAL, HAL lead free, Immersion gold, electrolytic gold, Immersion silver, Immersion Tin, OSP, Hard gold, Peelable, Carbon, metallized edges.
Principal materials FR4, Halogen, High Tg FR4	Kingboard, Shengyi, Iteq, Isola, Nelco, Ventec, Nan Ya, Tuc, Elite, Panasonic, Getek, Arlon, Rogers, Taconic, Wangling, Kingboard.
Hybrid materials	Rogers, Taconic, Arlon, Nelco with FR4
HDI board (High Density Interconnect)	1+N+1, 2+N+2, 3+N+3, Any layer HDI

Aluminum Printed Circuit board (IMS)	
Layers	1 & 2 layers
Minimum width track	0.125 mm
Minimum drilling diameter	0.80 mm
Maximum panel size	550 x 1500 mm
Board thickness finished	0.6, 0.8, 1.0, 1.2, 1.5, 2.0, 2.5, 3.0 mm
Copper thickness finished	35 & 70 µm
Surface finish	HAL lead free, Immersion gold, Immersion silver, Immersion Tin, OSP.
Principal Aluminum materials	Bergquist, Laird.
Thermal conductivity	1 W/mK, 1.2 W/mK, 1.5 W/mK, 1.6 W/mK, 2 W/mK, 3 W/mK.
Maximum thermal conductivity	12W/mK

Flexibles and Flex-rigid Printed Circuit Board	
Layers	30 layers flex, 20 layers flex-rigide + flex-rigide HDI
Minimum isolation	12 & 18µm (Cu start): 0.075/0.075mm - 35µm (Cu start): 0.1/0.1mm
Principal materials :	
FCCL (Flexible Copper Clad Laminate)	Shengyi, Dupont Pyralux & Panasonic
Coverlay	Shengyi & Taiflex
Adhesive	Shengyi & Taiflex
Stiffener	Polyimide Taiflex, FR4, or on request
CCL (Copper Clad Laminate)	Iteq, Shengyi, Arlon, Rogers, Nelco, Ventec
Tooling tolerances :	
Perforating tool	± 0.25mm
Precision tool	± 0.05mm
CNC drilling / routing	± 0,10 mm
Surface finish	HAL, HAL lead free, Immersion gold, electrolytic Gold, Immersion silver, Immersion Tin, OSP, Hard gold.
Flexible board thickness :	
Standard polyimid thickness	25,4-50,8 µm
Standard adhesive thickness	20 µm
Standard copper foil thickness	17,5-35 µm
Standard board thickness finished	0,13 mm
Flexible board maximum size :	
1 layer	500 x 1400 mm
2 layers	500 x 800 mm
Multi layers	220 x 630 mm
Maximum Copper Thickness	105 µm finished
Non plated holes tolerance	± 2mil (limite = +0/- 2 mil or +2/- 0 mil)